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(54) **ENCAPSULANT-DEFINED LAND GRID ARRAY (LGA) PACKAGE AND METHOD FOR MAKING THE SAME**

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(57) **ABSTRACT**

A method and related structure for a encapsulant defined land grid array (LGA) may comprise a semiconductor chip comprising conductive studs disposed over an active layer of the semiconductor chip, and a first encapsulant disposed around at least a portion of sidewalls of the conductive studs. A surface of the first encapsulant and conductive studs may be planarized. Conductive traces may be disposed over the encapsulant and coupled with the conductive studs. A dielectric layer may be disposed adjacent the conductive traces. LGA pads may be coupled with the conductive traces. A second encapsulant may be disposed over the dielectric layer and the LGA pads. A planar surface may be formed comprising the second encapsulant around the LGA pads and attachment areas on or over the LGA pads. The plurality of attachment areas may be coplanar or recessed the planar surface.